

Ref. S. M. Sze, "Physics of Semiconductor Devices"

2nd Edition, ISBN 0-471-05661-8, 1981

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p-n Junction Diode

is given by<sup>31</sup>

$$J_i = \frac{\sqrt{2m^*} q^3 \mathcal{E} V}{4\pi^2 \hbar^2 E_g^{1/2}} \exp\left(-\frac{4\sqrt{2m^*} E_g^{3/2}}{3q\mathcal{E}\hbar}\right) \quad (68)$$

where  $\mathcal{E}$  is the electric field at the junction,  $E_g$  the bandgap,  $V$  the applied voltage, and  $m^*$  the effective mass.

When the field approaches  $10^6$  V/cm in Ge and Si, significant current begins to flow by means of the band-to-band tunneling process. To obtain such a high field, the junction must have relatively high impurity concentrations on both the  $p$  and  $n$  sides. The mechanism of breakdown for Si and Ge junctions with breakdown voltages less than about  $4E_g/q$  is found to be due to the tunneling effect. For junctions with breakdown voltages in excess of  $6E_g/q$ , the mechanism is caused by the avalanche multiplication. At voltages between 4 and  $6E_g/q$ , the breakdown is due to a mixture of both avalanche and tunneling. Since the energy bandgaps  $E_g$  in Ge, Si, and GaAs decrease with increasing temperature (refer to Chapter 1), the breakdown voltage in these semiconductors due to the tunneling effect has a negative temperature coefficient; that is, the voltage decreases with increasing temperature. This is because a given breakdown current  $J_i$  can be reached at smaller reverse voltages (or fields) at higher temperatures, Eq. 68. A typical example is shown in Fig. 25. This temperature effect is generally used to distinguish the tunneling mechanism from the avalanche mechanism, which has a positive temperature coefficient; that is, the breakdown voltage increases with increasing temperature.

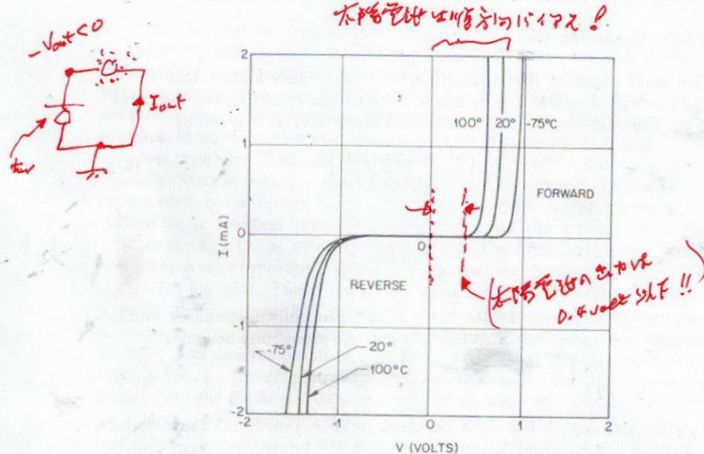
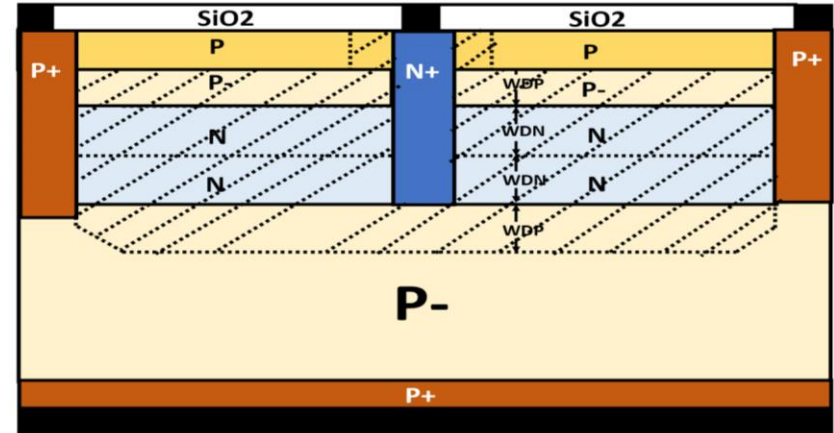


Fig. 25 Current-voltage characteristics of tunneling breakdown. (After Strutt, Ref. 32.)

## (A-type) Double P+PP-NP-P+接合型太陽電池

埋め込みN層と受光表面のP層には濃度制限がある。

P+N 接合間とN+P接合間にトンネル電流が流れない様に注意が必要。



## (B-type) Double P+PP-NP-P+接合型太陽電池

埋め込みN層と受光表面のP層には濃度制限がない。

しかし、MASK工程が増加し、生産コストが増す。

